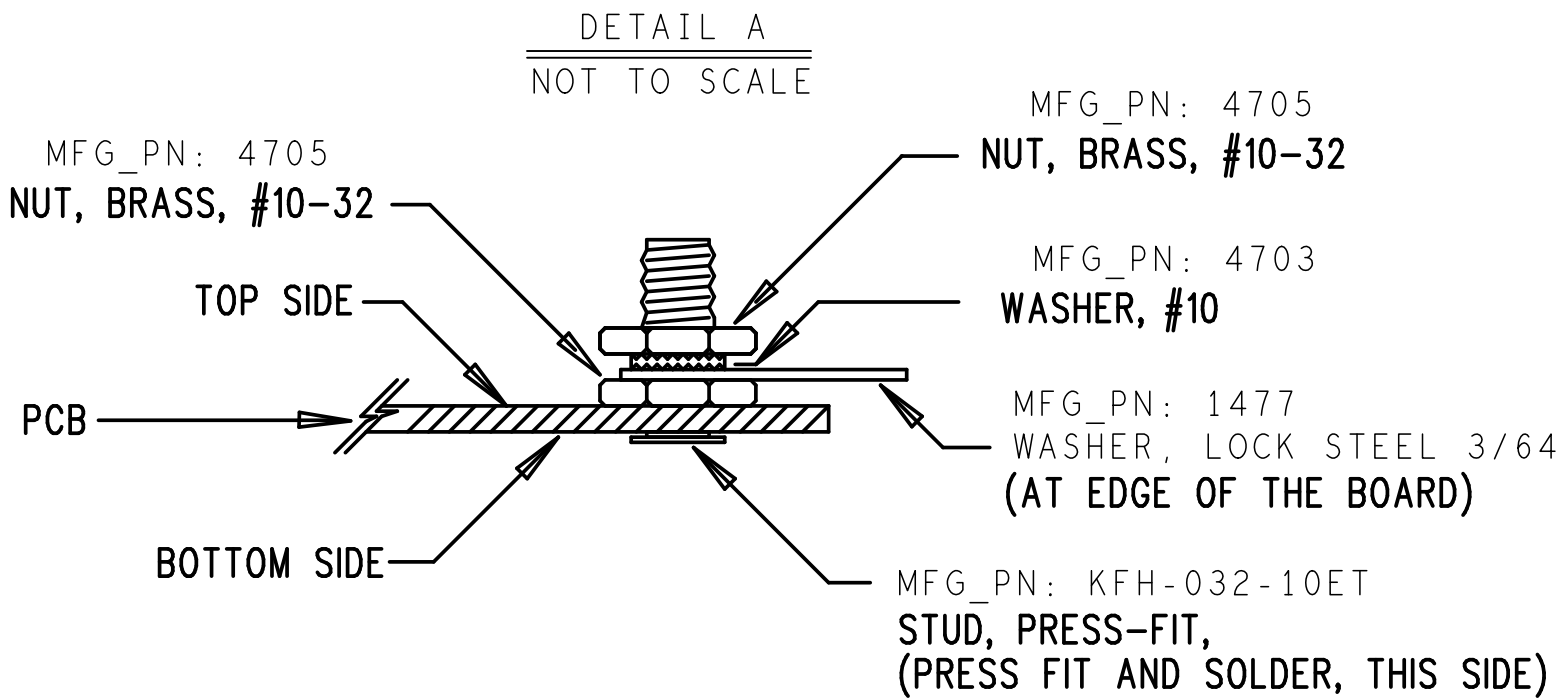


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	Initial Release	03Sep24	CR

ASSEMBLY NOTES:

- BOARD ACCEPTABILITY PER ANALOG DEVICES, INC. SPECIFICATION TST00119 (LATEST REVISION).
- REPAIRS PER IPC-7711/21(LATEST REVISION) ARE ALLOWED.
- REPAIRS ARE NOT ALLOWED IN SOLDERMASK FREE AREAS ON EITHER SIDE OF THE BOARD.
- RoHS COMPLIANCE: ASSEMBLY VENDOR SHOULD ASSURE COMPLIANCE WITH LEAD-FREE AND RoHS PCB ASSEMBLY STANDARDS (EU RoHS DIRECTIVE 2002/95/EC).
- SEE DETAIL A TO INSTALL KFH-032-10ET.




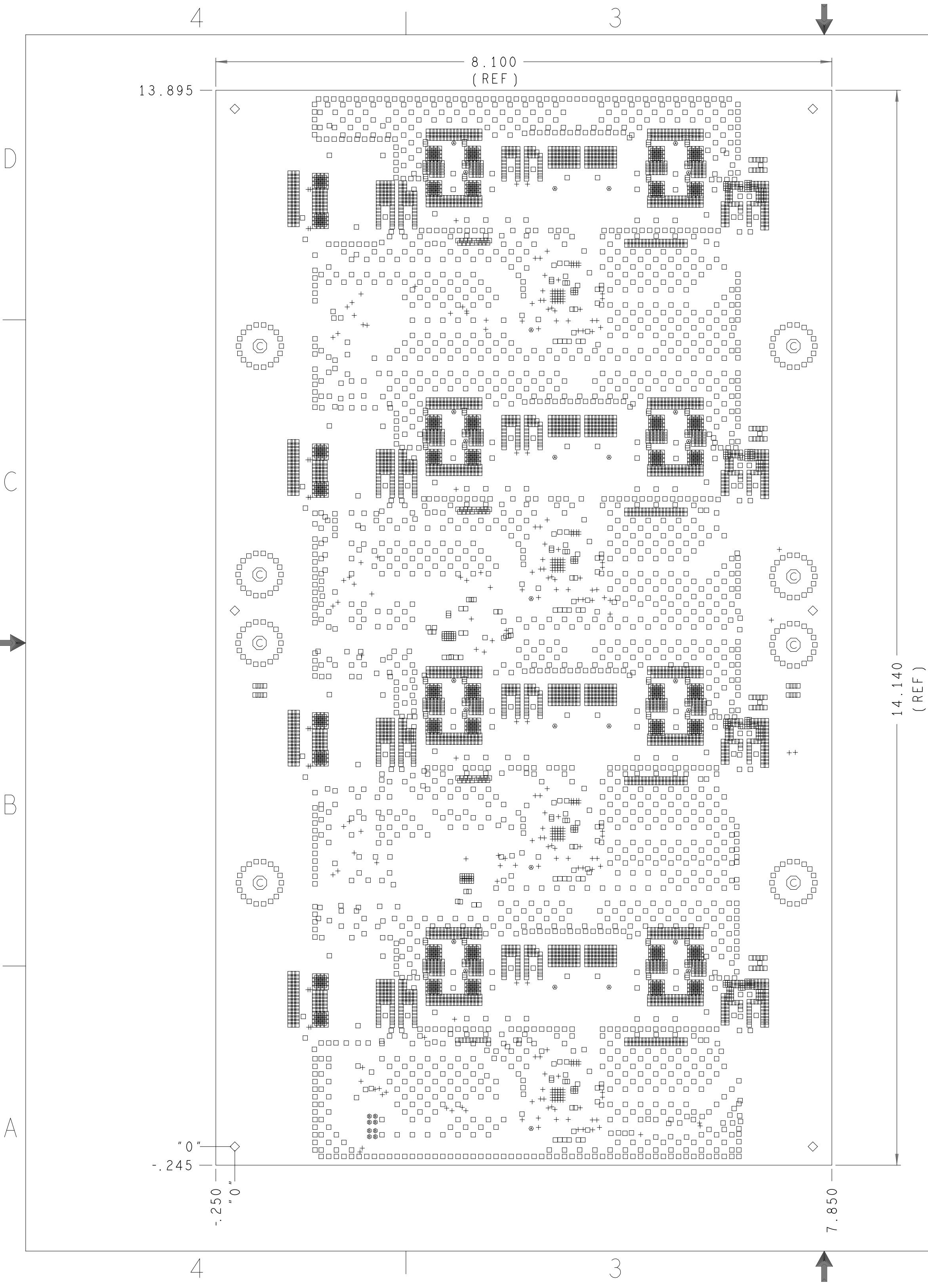
- INSTALL THE FOLLOWING:
SCREW (MFG_PN: NY PMS 440 0025 PH) AT PRIMARY SIDE AND
STAND-OFF (MFG_PN: 1902C) AT SECONDARY SIDE
- INSTALL THE FOLLOWING: SHUNT (MFG_PN: 2SN-BK-G)
JP1: PIN3 & PIN4
JP2: PIN3 & PIN4

SEE NOTE#5
8 PLACES

SEE NOTE#6
6 PLACES

PRIMARY SIDE

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES DECIMALS FRACTIONS ANGLES .XX -.010 +-1/32 +- 2 .XXX -.005 .XXXX -.0050 MATERIAL FINISH	APPROVAL		DATE		<div> ANALOG DEVICES</div> <div>WWM DIVISION 804 WOBURN STREET WILMINGTON, MA 01887</div>				
	TEMPLATE ENGINEER								
	HARDWARE SERVICES				TITLE ASSEMBLY EVAL-LT8210-1-AZ				
	HARDWARE SYSTEMS								
	TEST ENGINEER								
	COMPONENT ENGINEER								
	TEST PROCESS				SIZE FSCM NO DRAWING NUMBER REV C 01-080303 A				
	HARDWARE RELEASE								
	DESIGNER J Wu		03Sep24						
	PTD ENGINEER C Richie		03Sep24						
CHECKER									
DO NOT SCALE DWG				SCALE 1/1		SHEET 1 OF 1			




REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	Initial Release	03Sep24	CR

HOLE TOLERANCE
UNLESS SPECIFIED
PLATED: +/-3MILS
NON PLATED: +/-2MILS

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	PLATED	QTY	TOLERANCE/NOTES
+	10.0	PLATED	328	
□	12.0	PLATED	6707	
⊙	30.0	PLATED	28	
⊙	40.0	PLATED	8	
⊙	191.0	PLATED	8	
◇	125.0	NON-PLATED	6	

PRIMARY SIDE

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES DECIMALS FRACTIONS ANGLES .XX --.010 --1/32 -- 2 .XXX --.005 .XXXX --.0050	APPROVAL	DATE	<div><div>ANALOG DEVICES</div><div>WWM DIVISION 804 WOBURN STREET WILMINGTON, MA 01887</div></div> <div>TITLE FABRICATION EVAL - LT8210 - 1 - AZ</div>			
	TEMPLATE ENGINEER					
	HARDWARE SERVICES					
	HARDWARE SYSTEMS					
MATERIAL	TEST ENGINEER		SIZE	FSCM NO	DRAWING NUMBER	REV
	COMPONENT ENGINEER					
	TEST PROCESS					
	HARDWARE RELEASE					
FINISH	DESIGNER J Wu	03Sep24	C		09 - 080303	A
	PTD ENGINEER C Ritchie	03Sep24				
	CHECKER					
DO NOT SCALE DWG			SCALE	1 / 1		SHEET 1 OF 2

NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS ARE IN INCHES (EXCEPT WHERE NOTED).
ALL DOCUMENTS & SPECIFICATIONS REFERRED TO BELOW SHOULD BE THE LATEST REVISIONS.

RoHS COMPLIANCE NOTE: HOMOGENOUS MATERIALS IN THIS BOARD SHALL BE COMPLAINT WITH THE EU DIRECTIVE 2002/95/EC

MATERIAL :

2. BOARD MATERIAL:({USE CHECKED ITEMS})
- ☒

ISOLA 370HR OR S1000-2 OR IT180 OR EQUIVALENT
- ☐

ISOLA-FR408HR OR EQUIVALENT
- ☐

ISOLA IS410
- ☐

MEGTRON 6
- ☐

NELCO-4000-13
- ☐

ROGERS 4350B
- ☐

ROGERS 3003
- ☐

ARLON 85N
- ☐

EM370D
- ☐

OTHER _____

TOOLING:

8. IMPEDANCE REQUIREMENTS: IF NO STACKUP IS DEFINED, THE VENDOR IS ALLOWED TO ADJUST THE DIELECTRIC THICKNESS & TRACE WIDTHS TO MEET THE IMPEDANCE REQUIREMENT. IF SPECIFIED, THE VENDOR MUST MEET THE REQUIREMENTS LISTED IN THE IMPEDANCE TABLE. ANY ADJUSTMENT MADE TO THE DEFINED STACKUP, TRACE WIDTH & SPACING THAT IMPACT THE REQUIREMENTS MUST HAVE WRITTEN APPROVAL FROM ADI.
9. FILLET OPTIONS TO ENHANCE RELIABILITY AT PAD JUNCTIONS WHERE SPACING PERMITS.
() FILLETS ALLOWED
(X) FILLETS NOT ALLOWED
10. THIEVING:
() VENDOR MAY ADD THIEVING TO COMPENSATE FOR LOW COPPER DENSITY AREAS MAINTAINING A MINIMUM 0.100 INCH CLEARANCE FROM ALL COPPER FEATURES.
(X) VENDOR MAY NOT ADD THIEVING TO COMPENSATE FOR LOW COPPER DENSITY AREAS.
11. LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.003 INCHES.

FINISH:

12. DRILL SIZES ARE FINISHED HOLE SIZES. ALL HOLES SHALL BE LOCATED WITHIN 0.005 INCHES DTP,UNLESS SPECIFIED.
MINIMUM BARREL PLATING OF 0.001 INCHES. PLATED HOLES SHALL NOT BE ROUGH OR IRREGULAR SO AS TO HINDER PROPER SOLDER WICKING. BARREL RELIEF ON SOLDERMASK ALLOWED IN UNFILLED VIA IN PAD HOLES.
13. PLATING SPECIFICATION:
(X) REFER TO LAMINATION DIAGRAM FOR FINISHED COPPER WEIGHT/THICKNESS REQUIRMENTS
THE STARTING COPPER WEIGHT/THICKNESS CAN VARY AS LONG AS THE FINISHED COPPER WEIGHT/THICKNESS IS NOT LESS THAN THE SPECIFIED VALUE.
14. SURFACE FINISH:
(X) IMMERSION GOLD (ENIG) 1.58-3.94 MICRO INCHES OVER 118-236 MICRO INCHES MIN. OF ELECTROLESS NICKEL PER IPC-4552
() OSP (ORGANIC SOLDERABILITY PRESERVATIVE)
() IMMERSION SILVER
() SOFT WIRE BONDABLE GOLD 30-50 MICRO INCHES OF SOFT WIRE
BONDABLE GOLD OVER 100-150 MICRO INCHES OF NICKEL
() EDGE CONNECTOR FINGERS ARE TO BE PLATED WITH 100 MICRO-INCHES(.0001") OF LOW STRESS NICKEL UNDER 30 MICRO-INCHES (.0003") OF GOLD
() OTHER_____
15. SOLDERMASK:
SOLDERMASK OVER BARE COPPER OR BARE GOLD (BOTH SIDES) TO MEET IPC-SM-840.
IF PRESENT,DO NOT MODIFY SOLDERMASK DEFINED PADS (MASK OPENINGS LESS THAN COPPER PAD) WITHOUT APPROVAL.
(X) LPT
() OTHER_____
- COLOR
(X) GREEN
() OTHER_____
16. APPLY SILKSCREEN TO BOTH SIDES USING A NON-CONDUCTIVE, EPOXY BASED INK PER ARTWORK.
(X) WHITE
() OTHER

TESTING:

17. FINAL ELECTRICAL TEST TO BE PERFORMED USING PROVIDED IPC-D-356A NETLIST OR ODB++ FORMAT FILE.
THE PCB SHALL HAVE A VERIFICATION STAMP.
18. A TIME DOMAIN REFLECTOMETER REPORT (TDR) FOR EACH IMPEDANCE CONTROLLED LAYER & A CERTIFICATE OF COMPLIANCE SHALL BE PROVIDED BY VENDOR AT TIME OF SHIPMENT. INSTANCES WHERE TDR TESTING CAN'T BE PERFORMED BECAUSE THE TRACE LENGTH IS TOO SHORT ON THE OUTER LAYERS AT THE PIN ESCAPES IS ACCEPTABLE. ALL OTHER INSTANCES MUST BE REPORTED.

MISCELLANEOUS:

19. IF PRESENT, ALL BLIND/BURIED VIAS WITH AN ASPECT RATIO <1:1 TO BE PLATED SHUT WITH COPPER WHEN USED AS VIA-IN-PAD OR AS A STACKED VIA. BLIND/BURIED VIAS WITH AN ASPECT RATIO >1:1 TO BE FILLED WITH NON-CONDUCTIVE EPOXY.
20. FOR VIA FILL INFORMATION REFER TO DRILL CHART:
() NON-CONDUCTIVE EPOXY FILL ALL 0.XXXX INCHES DRILLED VIAS
() COPPER FILL ALL 0.XXXX INCHES DRILLED VIAS
21. INTENTIONAL SHORTS:
IF AN INTENTIONAL SHORT REPORT IS SUPPLIED AND DOES NOT MATCH THE FAB DATA THEN ADI APPROVAL IS REQUIRED.
22. PEMNUTS:
() PEMNUTS TO BE INSTALLED BY FABRICATOR
() PEMNUTS NOT TO BE INSTALLED BY FABRICATOR
(X) NOT APPLICABLE
23. MANUFACTURER TO ETCH/STAMP WITH PERMANENT NON-CONDUCTIVE INK ON SECONDARY SIDE UNLESS OTHERWISE SPECIFIED:
A. UL CODE-FLAMMABILITY RATING FOR THOSE APPROVED MATERIALS(IF APPLICABLE)
B. DATE CODE
C. LOT NUMBER
D. MANUFACTURER LOGO

~~25. PANELIZATION:~~

~~BOARDS TO BE SHIPPED IN ARRAY AND KEPT INTACT~~

~~PANEL TO BE SUBJECTED TO CUSTOMERS APPROVAL~~

~~PANEL SOLDER PASTE STENCIL GERBER TO BE PROVIDED TO ANALOG~~

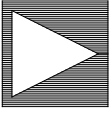
27. MINIMUM DESIGN LINE WIDTH IS .008 INCH.
28. MINIMUM DESIGN LINE SPACING IS .008 INCH.

FAB NOTES REVISION: 2ND NOVEMBER 2022

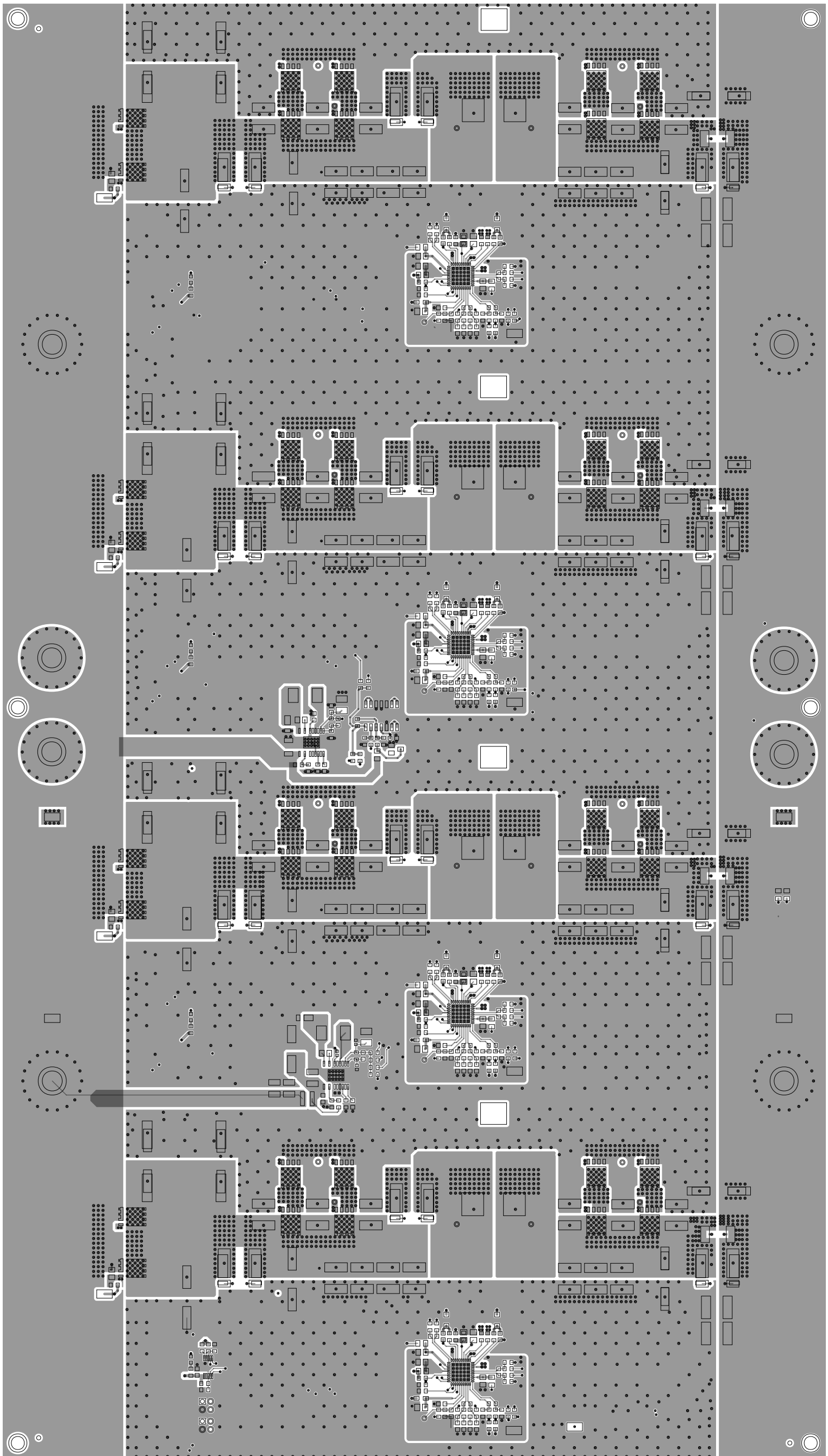
6-LAYER STACK-UP

LAMINATION DIAGRAM				
LAYER NUMBER	LAYER NAME	COPPER THICKNESS (OZ, INCH)	DIELECTRIC THICKNESS (INCH)	MATERIALS
1	TOP	2 OZ, 0.0024"		FINAL CU (THICKNESS AFTER PLATING)
			0.008	ISOLA 370HR/EQUIVALENT
2	L2_GND	1 OZ, 0.0012"		CU CLAD
			0.008	ISOLA 370HR/EQUIVALENT
3	L3_SIG	1 OZ, 0.0012"		CU CLAD
			0.0196	ISOLA 370HR/EQUIVALENT
4	L4_GND	1 OZ, 0.0012"		CU CLAD
			0.008	ISOLA 370HR/EQUIVALENT
5	L5_VCC	1 OZ, 0.0012"		CU CLAD
			0.008	ISOLA 370HR/EQUIVALENT
6	BOTTOM	2 OZ, 0.0024"		FINAL CU (THICKNESS AFTER PLATING)
THE FINISHED PCB THICKNESS TO BE: 0.062" +/-10%				

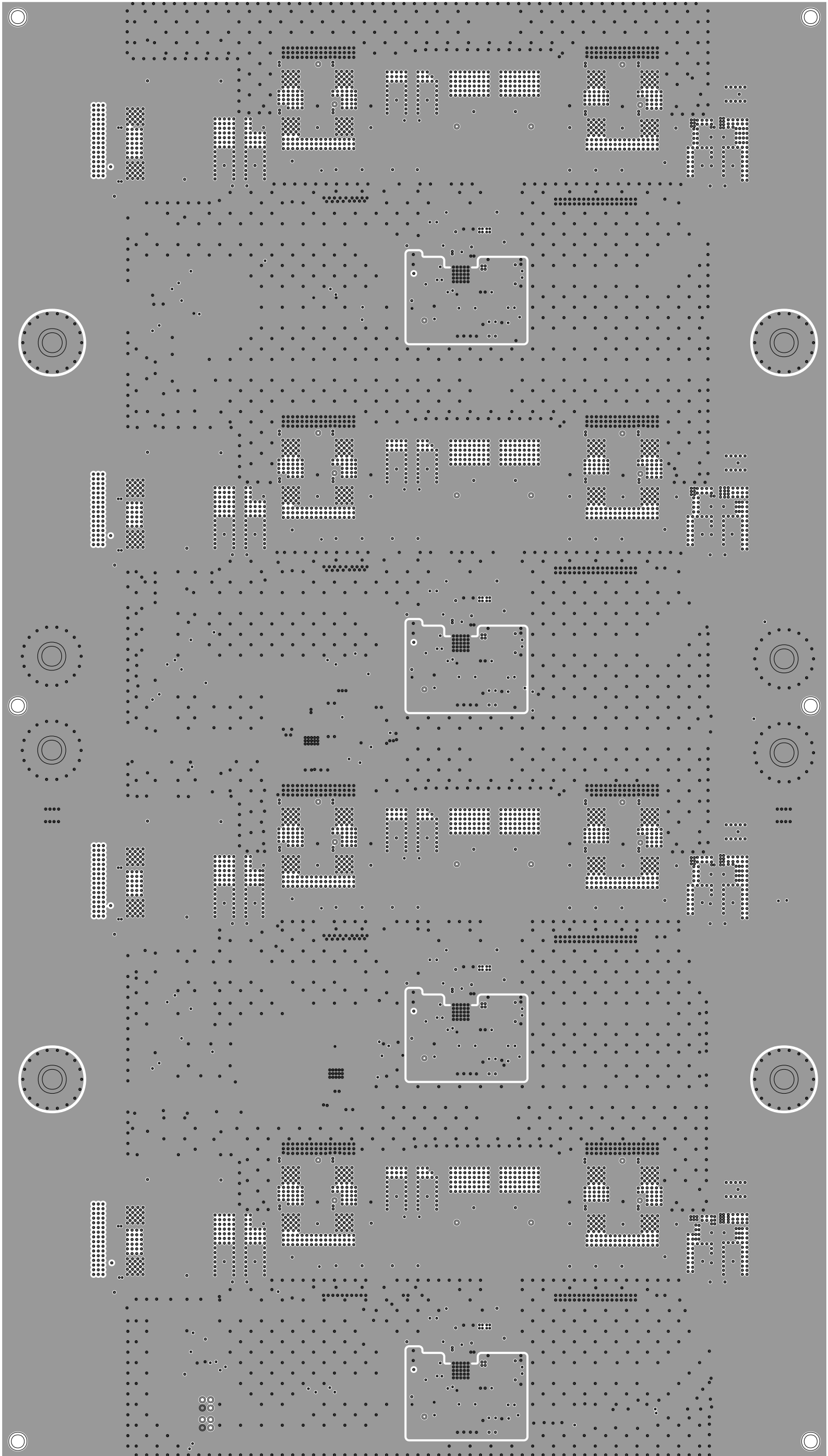
PRIMARY SIDE

		ANALOG DEVICES		WWM DIVISION 804 WOBURN STREET WILMINGTON, MA 01887	
		SIZE	FSCM NO	DRAWING NUMBER	REV
C		24355	09-080303	A	
SCALE		1/1		SHEET	2 OF 2

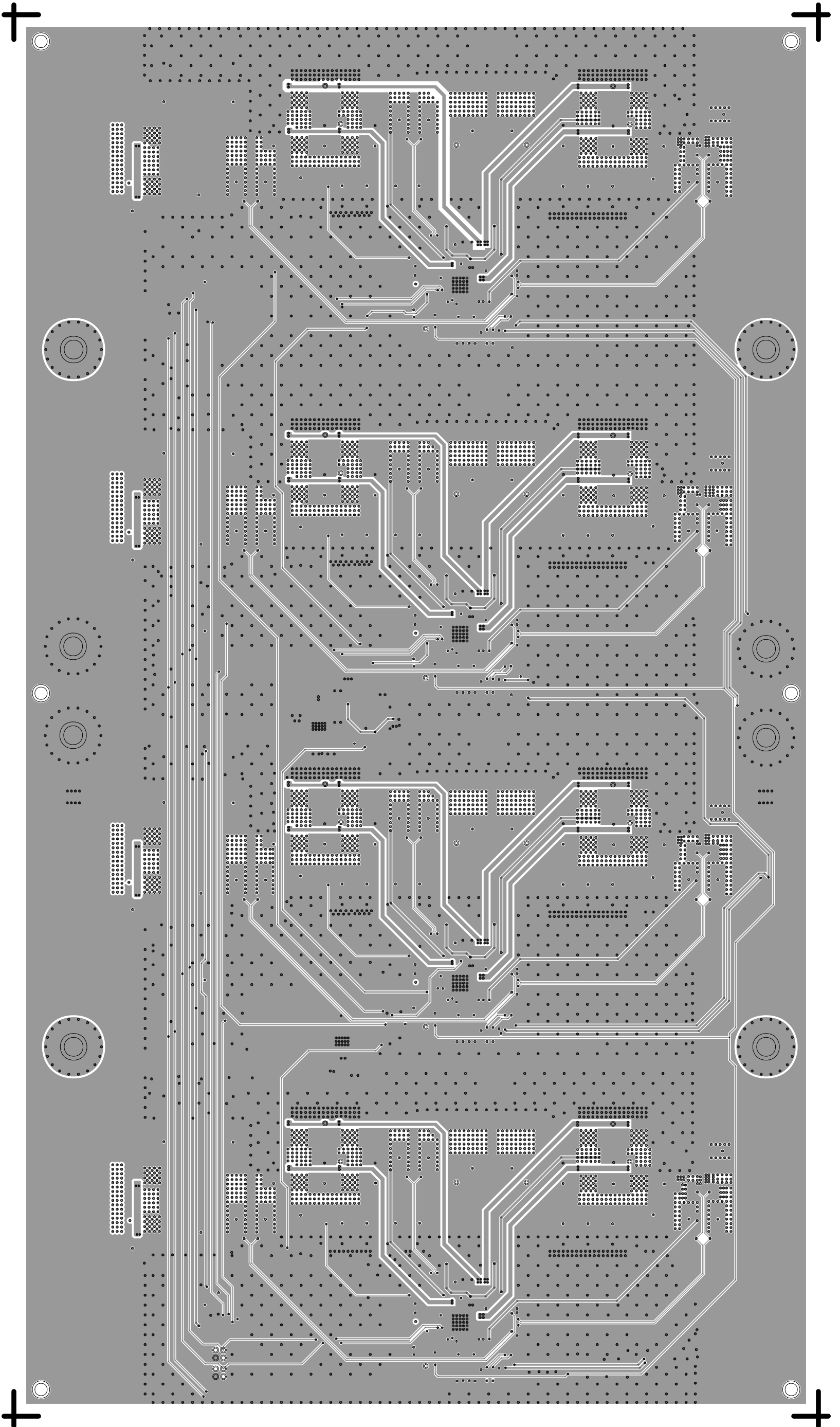
L1 PRIMARY
08-080303-01
REV A



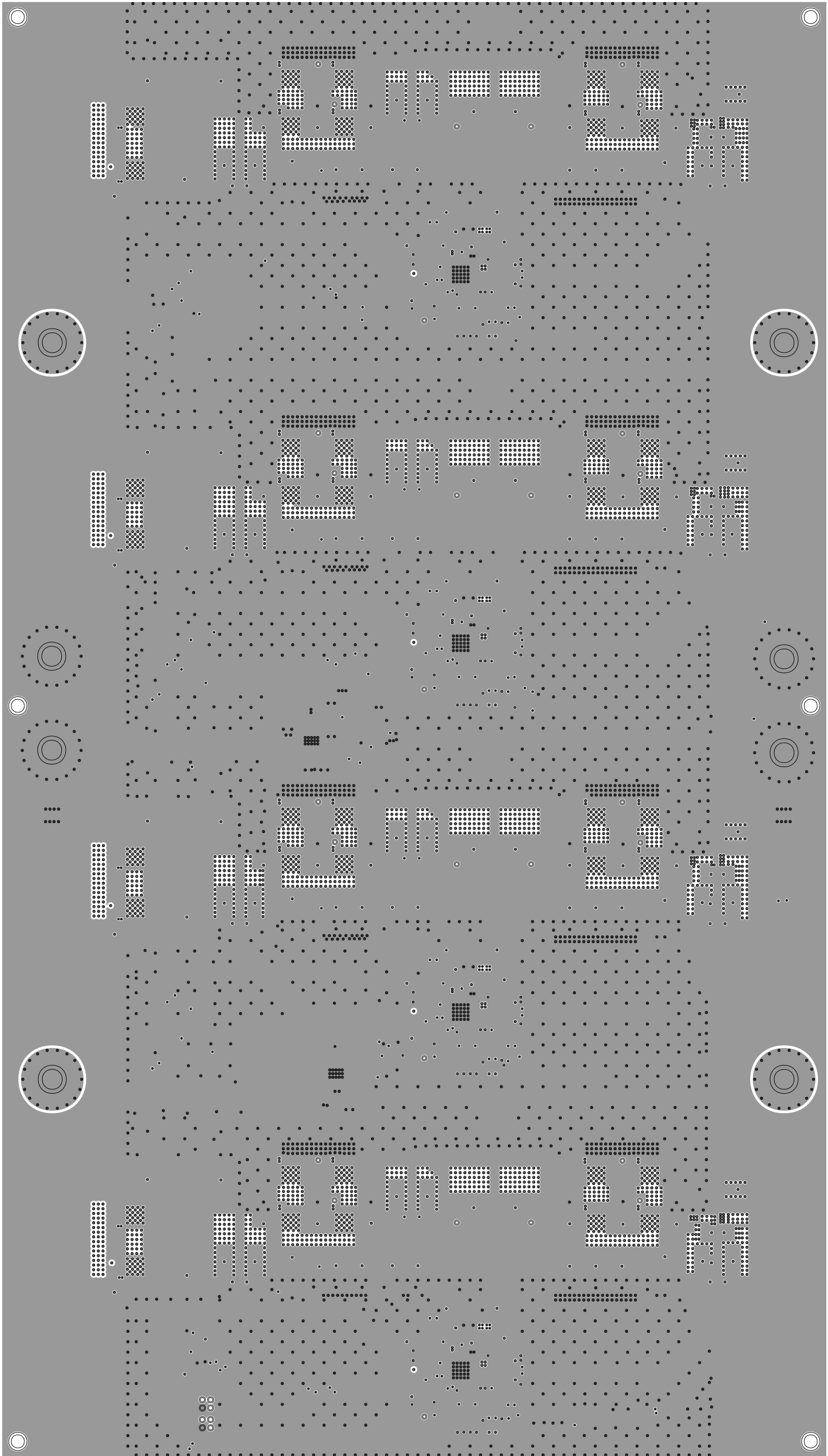
L2 GND
08-080303-06
REV A



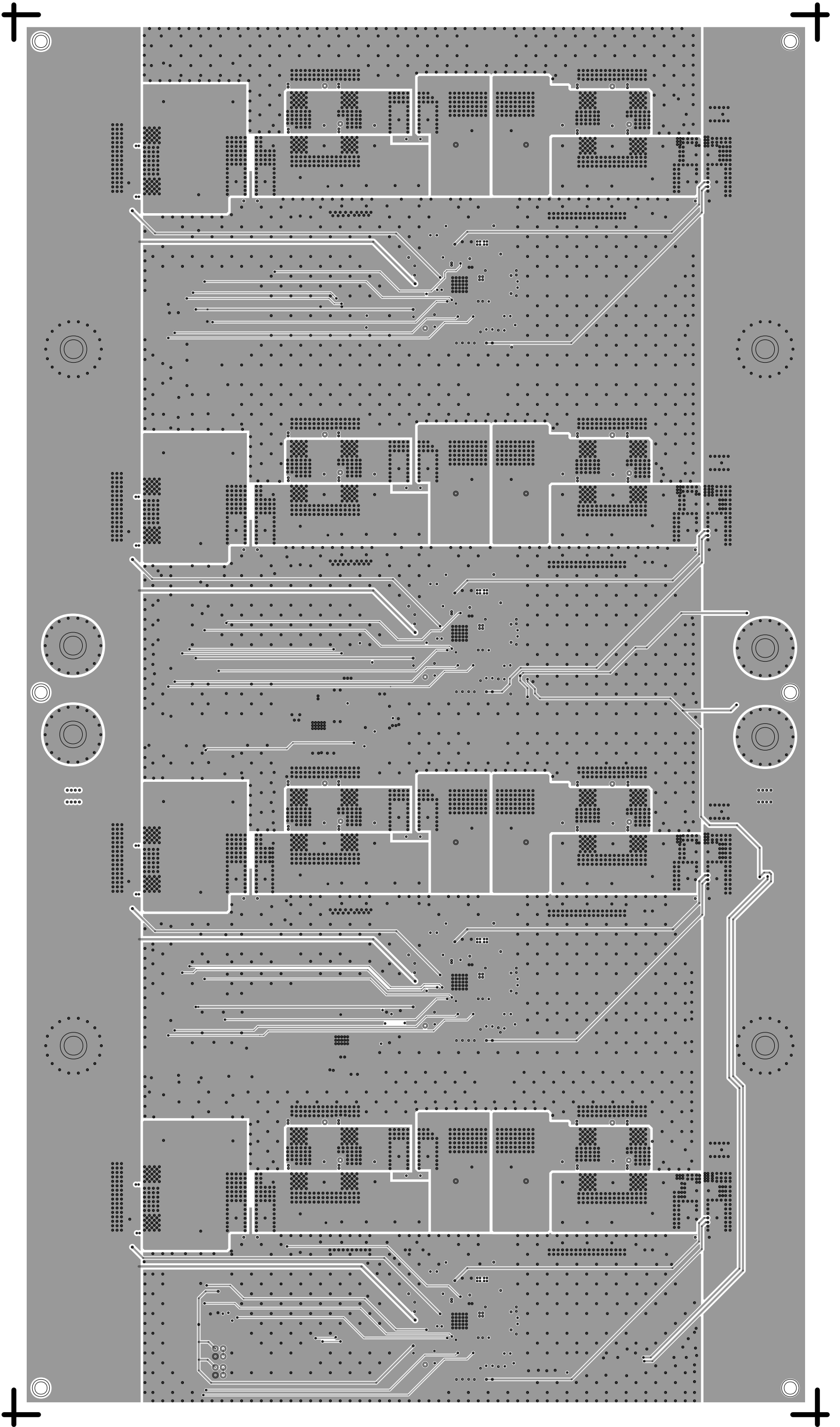
L3 SIG
08-080303-07
REV A

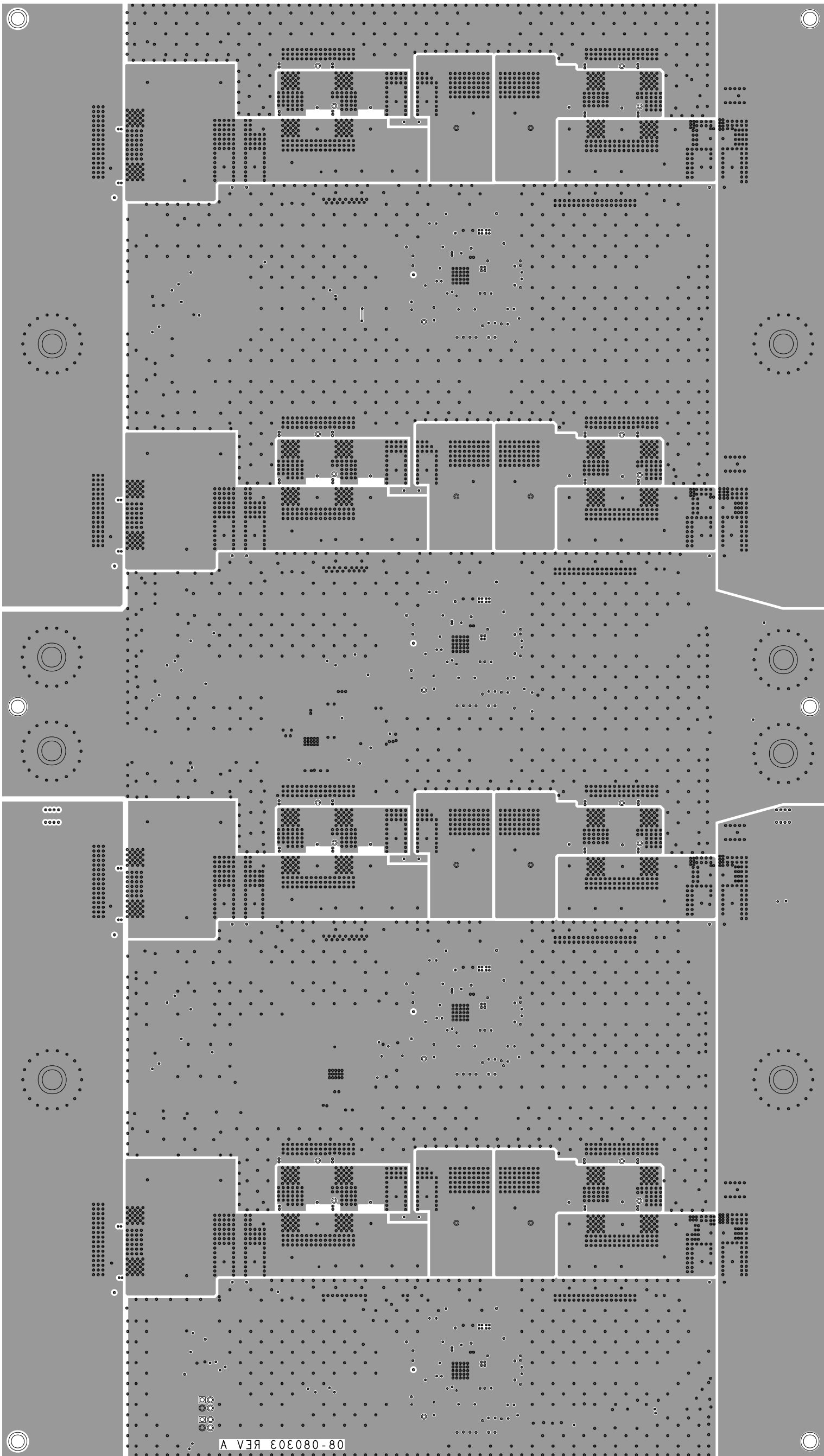


L4 GND
08-080303-08
REV A

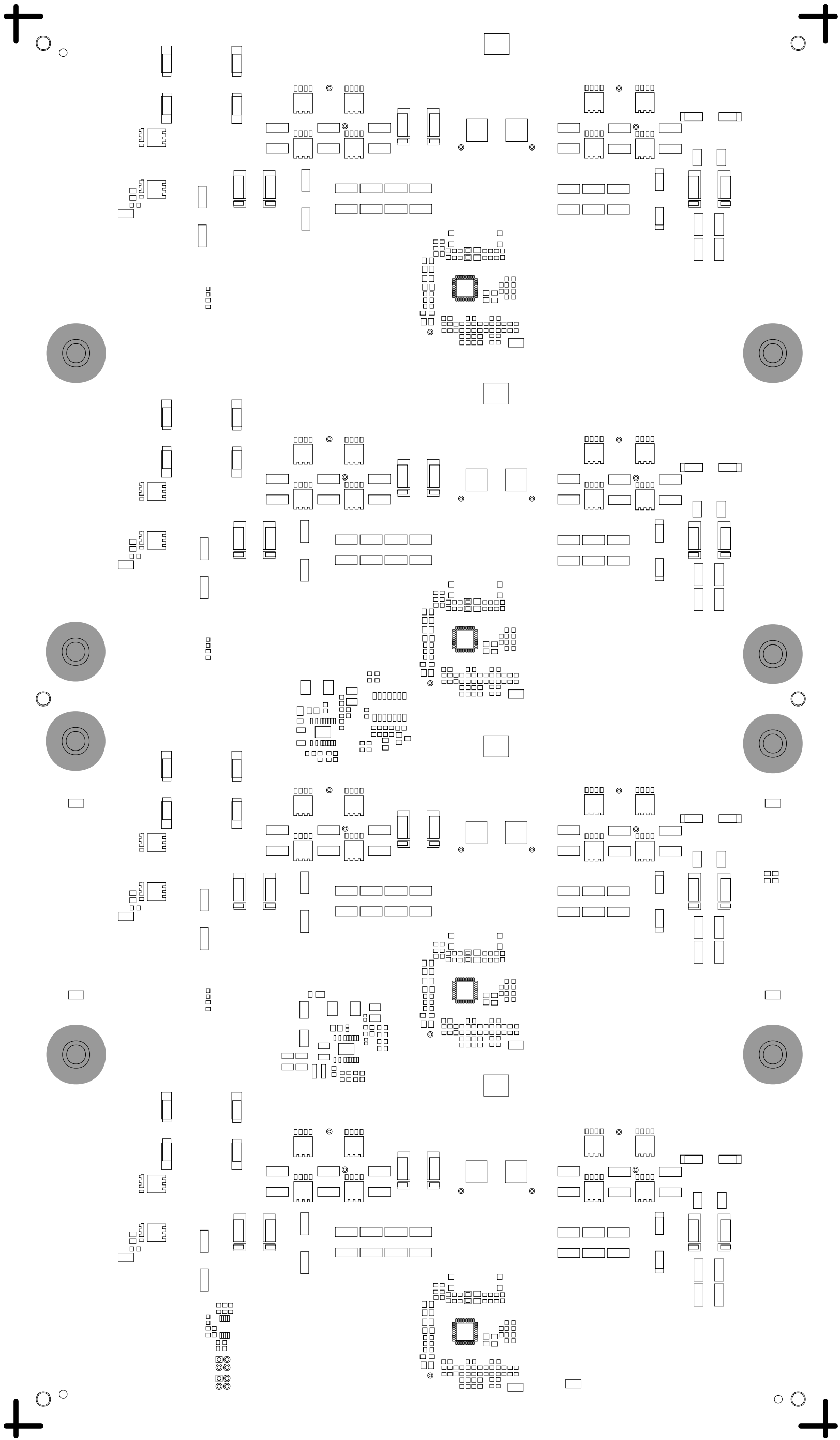


L5 VCC
08-080303-09
REV A

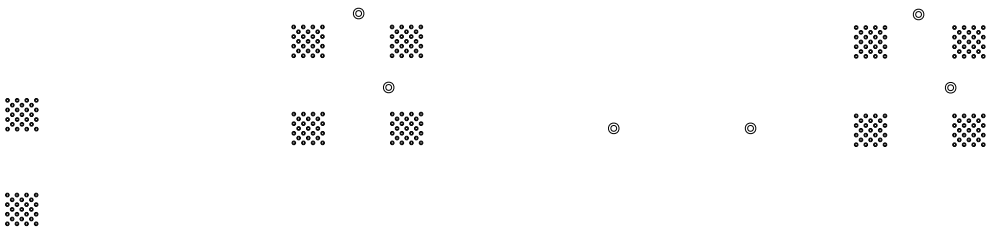
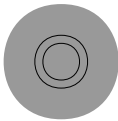
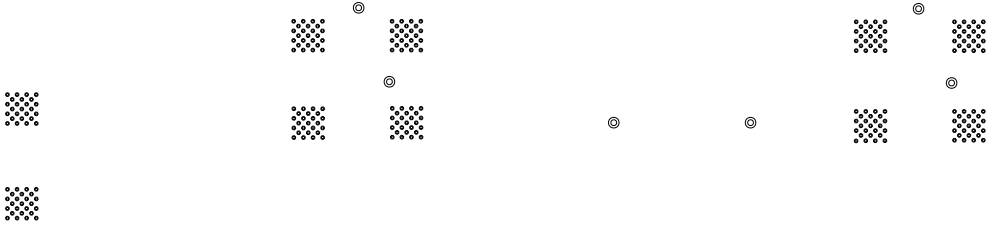
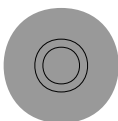
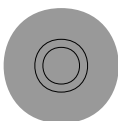
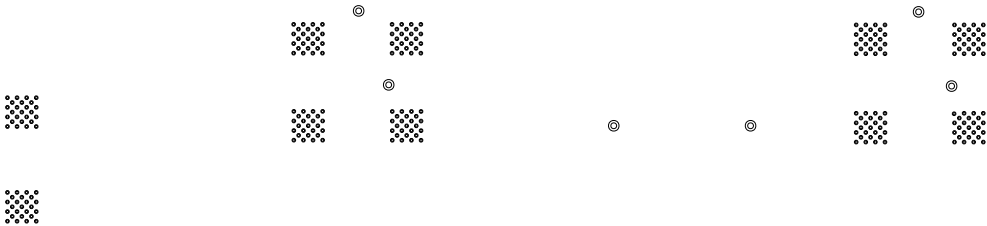
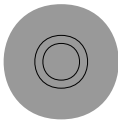
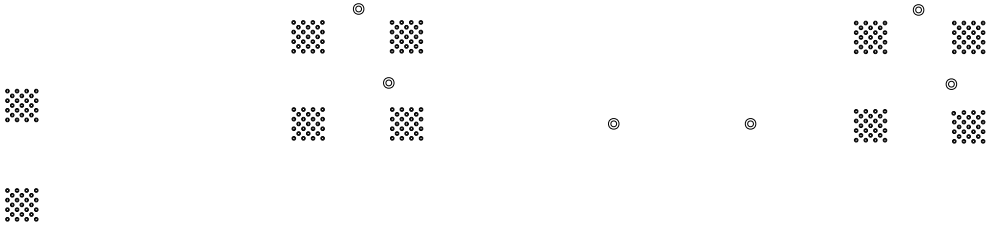




SOLDERMASK PRIMARY
08-080303-04
REV A



SOLDERMASK SECONDARY
08-080303-05
REV A



PASTEMASK PRIMARY
08-080303-10
REV A

